

IN THE CLAIMS:

Please amend claim 2 to read as follows:

1. (Previously Presented) Blister package arrangement with a blister package and a conductor carrier strip connected to it, wherein openings in the conductor carrier strip are directed toward pockets of the blister package, and wherein, upon removal of a tablet from a pocket, a sealing film of the blister package sealing the pocket must be separated, and the tablet is removable through an opening assigned to it, the improvement wherein the openings are formed by stamped lines positioned within the conductor carrier strip that surround each of the pockets in a ring shape, and that are interrupted by at least two spars by means of which a covering, separated by the stamped line out of the conductor carrier strip and covering the pocket, is connected with the conductor carrier strip; wherein the spars are so distributed about the periphery of the stamped line that, when a tablet is pressed out from a pocket, at least one spar is severed; and wherein the conductor carrier strip includes individual conductors each of which extends from an

individual connecting pad over at least the one spar that is severed upon tablet removal.

2. (Previously Presented) Blister package arrangement as in Claim 1, wherein each individual conductor, at its end opposite its associated individual connection pad, is connected with a common conductor which is connected to a common connection pad.

3. (Currently Amended) Blister package arrangement as in Claim 2, wherein the individual connecting pads and a the common connection pad are components of an interface, which upon insertion of the blister package arrangement in the a receiver device, effect a defined position orientation and are is electrically connected with an electronic unit in the receiver device to detect the severance of the individual conductors.

4. (Previously Presented) Blister package arrangement as in Claim 1, wherein the stamped lines have a shape selected from the group consisting of rectangular, circular, and oval.

5. (Previously Presented) Blister package arrangement as in Claim 1, wherein the spars are positioned diametrically opposite each other about the circumference of the stamped line, and wherein the individual conductor associated therewith extends over both spars.

6. (Previously Presented) Blister package arrangement as in Claim 5, wherein the two spars each lie along the direction of the longer extension of the stamped line.

7. (Previously Presented) Blister package arrangement as in Claim 6, wherein the individual conductor extends over the first and the additional spars.

8. (Previously Presented) Blister package arrangement as in Claim 1, wherein the individual conductor extends only over one of the spars from the conductor carrier strip to the covering, and from the covering back to the conductor carrier strip as a loop, whereby the conductor-bearing spar is positively severed upon tablet removal.

9. (Previously Presented) Blister package arrangement as in Claim 1, wherein the conductor carrier strip includes the individual conductors on the side facing away from the

blister package, and is attached to the side facing toward the blister package by means of the sealing film of the blister package.

10. (Previously Presented) Blister package arrangement as in Claim 9, wherein the conductor carrier strip is at least partially provided with an electrically insulating protective layer on its side facing away from the blister package that covers at least the individual conductors and a common conductor.

11. (Previously Presented) Blister package arrangement as in Claim 1, wherein the conductor carrier strip includes the individual conductors on its side facing toward the blister package, and that the side of the conductor carrier strip facing toward the blister package is provided with an electrically insulating layer covering the individual conductors, and wherein the side of the electrically insulating layer facing toward the blister package is connected with the sealing film of the blister package.

12. (Previously Presented) Blister package arrangement as in Claim 11, wherein the electrically insulating layer is

provided with an adhesive layer that may be connected with the sealing film of the blister package.

13. (Previously Presented) Blister package arrangement as in Claim 12, wherein the adhesive layer is covered by a tear film that may be separated from the adhesive layer in order to connect the adhesive layer to the sealing film.

14. (Previously Presented) Blister package arrangement as in Claim 2, wherein the conductor carrier strip projects over the blister package at least on the side of the interface.

15. (Previously Presented) Blister package arrangement as in Claim 1, wherein the conductor carrier strip forms a first component of the carrier strip that folds like a book, and a second component forms at least one of an insertion opening for each pocket of the blister package and a common insertion opening for all pockets of the blister package, and may be folded about a fold line with respect to the conductor carrier strip so that the blister package is accepted between the conductor carrier strip and the second part, whereby each pocket of the blister package extends through an insertion opening of the second component or all

pockets of the blister package through the common insertion opening of the second component, and wherein the conductor carrier strip, the blister package, and the second component receiving the pockets of the blister package are connected with each other.

16. (Previously Presented) Blister package arrangement as in Claim 15, wherein the conductor carrier strip and the second component project over the blister package at least on the side of an interface of the conductor carrier strip with a receiver device.

17. (Previously Presented) Blister package arrangement as in Claim 15, wherein the conductor carrier strip and the second component project over the blister package on all sides.

18. (Previously Presented) Blister package arrangement as in Claim 15, wherein the fold line extends along the longer side of the conductor carrier strip and the second component.

19. (Previously Added) Blister package arrangement as in Claim 15, wherein the conductor carrier strip, the blister

package and the second component receiving the pockets of the blister package are adhered together.

20. (Previously Added) Blister package as in Claim 11, wherein the electrically insulating layer is simultaneously an adhesive layer that may be connected to the sealing film of the blister package.